g		GE Energy		Function	al Testing Sp	ecification	
	Parts & Repal Louisville, KY	ir Services	_	LOU-	GED-531X129SN	CADG1	
	Test Procedure for a snubber card						
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3/10/2	2010	DATE	DATE		3/10/2010		

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	Louisville, KY	

1. SCOPE

1.1 This is a functional testing procedure for a snubber card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

- **3.1** The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
 - **3.1.1** Filename; 129snc.doc located in electronic folder.

4. **ENGINEERING REQUIREMENTS**

- 4.1 Equipment Cleaning
 - **4.1.1** Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
- **4.2** Equipment Inspection
 - **4.2.1** Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
 - 4.2.1.1 Wires broken, cracked, or loosely connected
 - 4.2.1.2 Terminal strips / connectors broken or cracked
 - 4.2.1.3 Components visually damaged
 - **4.2.1.4** Capacitors bloated or leaking
 - 4.2.1.5 Solder joints damaged or cold
 - 4.2.1.6 Circuit board burned or de-laminated
 - 4.2.1.7 Printed wire runs / Traces burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)

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TESTING PROCESS

6.

REV. A

6.1 Testing Procedure

- 6.1.1 Verify that C1, C2, C3 and C4 are .47uf 1000V capacitors (104X122AA244). Verify that they are securely tie-wrapped to the board.
- 6.1.2 Verify that R3, R4 and R5 are FS-205-5 NI (5%) or equivalent (104X123DA075) resistors.
- 6.1.3 Verify that R1 and R2 are 0.1 ohm 10% 20W NI or equivalent (104X123DA076) resistors. They can also consist of (3) .27-ohm PW5 resistors soldered in parallel.
- 6.1.4 Verify that D1, D2, D3, D4, D5, D6, D7 and D8 are SRP600K or equivalent (104X125AA159) diodes, that they are assembled per the top stamp and using an ohmmeter with a diode testing scale, verify that they are not shorted.
- Verify that P1-T stab-on (104X161AC103) is present 6.1.5
- 6.1.6 Verify that wire jumpers J1 and J2 are present and correctly soldered
- 6.1.7 Verify that all four buss bar connectors (E2, C2, C1 and E1) (44B962815002) are present and correctly soldered.
- 6.1.8 Verify that all parts are mounted against the board
- 6.1.9 Verify that all parts are soldered to the board and that no bridges exist between the etchings.

6.2 ***TEST COMPLETE ***

7. NOTES

7.1 None at this time.

ATTACHMENTS

8.1 None at this time.